C-Grid Connectors

C-Grid is a dual-row board-to-board connector system that features a low-profile design and a wide range of circuit sizes in vertical and right-angle configurations, making these connectors suitable for diverse low power and signal applications

Features and Advantages Low profile C-Grid Connectors in 2 to 80 circuit sizes, single- and dual-rows, vertical and horizontal configurations and various plating options Receptacle Offer design flexibility (Series 71850) 9.40mm Header (Series 70246) C-Grid Connectors Header (Series 71349) 13.80mm **Reflow capable headers** Receptacle Delivers high-temperature assembly processing (Series 71395) C-grid headers are compatible with SL housings C-Grid headers mate with SL housings to offer secure wireto-board connection SL Crimp Housing (Series 70450) C-Grid Right-Angle Header SL Crimp Housing (Series 70247) (Series 70450) **C-Grid Vertical Header** (Series 70246)

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Markets and Applications

Automotive

Audio, navigation, infotainment Car LCD panel

Consumer

Microwave ovens Washers and dryers White goods

Data/Communications

Analytical chemistry:

GC, CE, Capillary LC, Flow cytometry

Lighting

Architectural lighting Industrial lighting Office lighting

Medical

ECG or EEG machines Respirators

Specifications

REFERENCE INFORMATION

Reference Information Packaging: Bag, Tray, Reel UL File No.: E29179 CSA File No.: LR19980 Mates With: Series 70246/70247/70567/75101/70568/ 87834/74164 with series 71850 Series 71349/74162/74164 with series 71395 Designed In: Millimeters RoHS: Yes

Networking

1U rack boxes Blade servers Rack-mount servers Routers and switches Storage racks



White Goods



Oven



Office Lighting



Car Infotainment



Servers

ELECTRICAL

Voltage (max.): 250V Current (max.): 3.0A Contact resistance: 10 milliohms Dielectric Withstanding Voltage: 600V Insulation Resistance: 1000 Megohms

MECHANICAL

Pitch: 2.54mm Pin retention force (min.): 1.81kgf (before soldering) Durability: -25 cycles (Tin plating) -50 cycles (Gold plating) PHYSICAL

Housing: LCP Contact: High Copper Alloy Plating: Gold (Au) or Tin (Sn) over Nickel Operating Temperature: -40 °C to +105 °C (Tin plating) -55 °C to +120 °C (Gold plating)

www.molex.com/link/cgrid.html

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